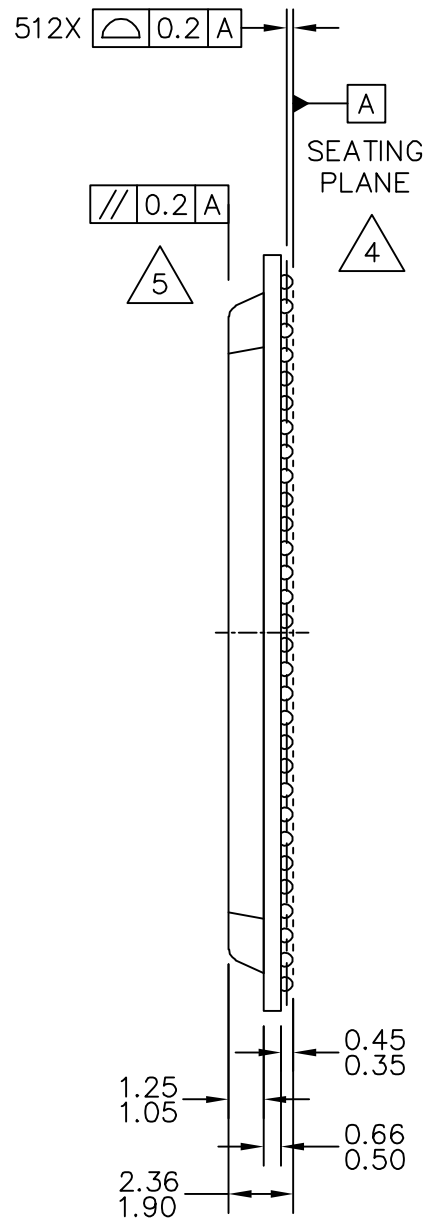
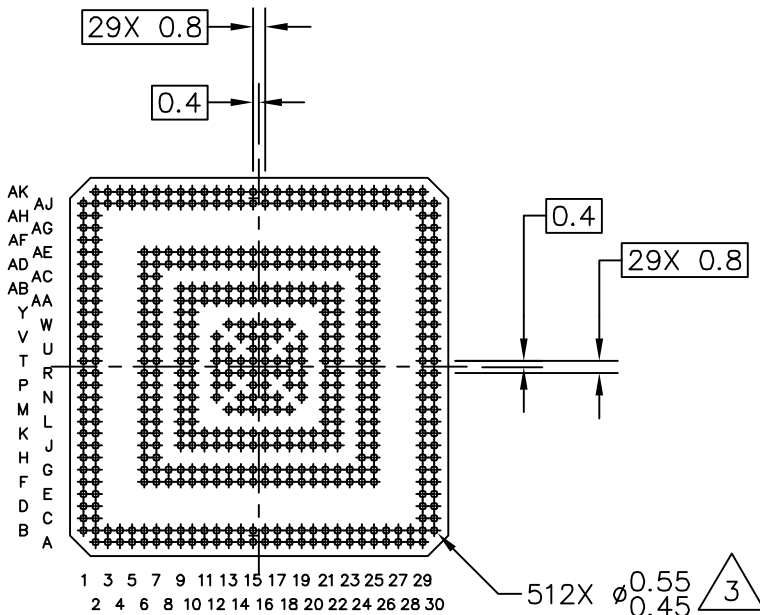


TOP VIEW



SIDE VIEW



BOTTOM VIEW

ϕ	$\phi 0.15(M)$	A	B	C
	$\phi 0.08(M)$	A		

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TITLE: TEPBGA-I, 25 X 25 PKG, 0.8 MM PITCH, 512 I/O	DOCUMENT NO: 98ASA00262D	REV: A
	STANDARD: NON JEDEC	
	SOT1716-1	08 JAN 2016



NOTES:

1. ALL DIMENSIONS IN MILLIMETERS.
2. DIMENSIONING AND TOLERANCING PER ASME Y14.5M-1994.
3. MAXIMUM SOLDER BALL DIAMETER MEASURED PARALLEL TO DATUM A.
4. DATUM A, THE SEATING PLANE, IS DETERMINED BY THE SPHERICAL CROWNS OF THE SOLDER BALLS.
5. PARALLELISM MEASUREMENT SHALL EXCLUDE ANY EFFECT OF MARK ON TOP SURFACE OF PACKAGE.

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